TTL Military Logic Delay Module (Thinny)

The TTL Military Logic Delay Modules (Thinny) manufactured by Engineered Components Company are designed to provide output waveforms that reproduce the input waveform after a set amount of delay time has elapsed. The five output waveforms are delay line taps provided at 20% increments of the total delay (20, 40, 60, 80, and 100%). These delay modules are non-inverting. The delay times are calibrated to the listed tolerances on the rising edge delays (see the Product Selection Table).

The MTBF on these modules, when calculated per MIL-HDBK-217, for a 50 deg.C ground fixed environment and with 50VDC applied, is in excess of 3 million hours. The temperature coefficient of delay is less than 500 ppm/deg.C over a temperature range of -55 to +100 deg. C. These modules are designed to operate over the full military temperature range of -55 to +125 deg. C.

The module is provided in a 14-pin DIP package, fully encapsulated in epoxy resin and is housed in a Diallyl Phthalate case, red in color. The case marking is applied by silkscreen using white epoxy paint. The 8 copper leads are tin-lead plated and meet the solderability requirements of MIL-STD-202, Method 208.

**BLOCK DIAGRAM**

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